

SUNBONDER®

ULTRASONIC SOLDERING SYSTEM USM-5 series

Ultrasonic soldering makes it possible to solder glass, ceramics and low-solderability metals, such as Al, Mo, stainless steel etc.

Common Specification

【 GENERATOR 】

Ultrasonic-power	1~12W (0.1W interval)
Temperature range	OFF、200°C~ (10°C interval)
Display	Frequency,US Power,Temperature,Amplitude
External monitoring	Temperature, US Power (0-10V)
Power Requirements	AC100V/240V, 50/60Hz

【 IRON 】

Tranducer	Langevin type
Tip material	Stainless steel
Heater	High performance sheathed heater

※The tip shape is supported nonstandard type.

LINE-UP



Detail Specification

		USM-560	USM-540	USM-528
US	Frequency	60kHz	40kHz	28kHz
US power	max	12W	12W(no load) 20W(soldering)	12W(no load) 70W(soldering)
Generator	SIZE	210 x 235 x 90		260 x 320 x 140
	Weight	5kg		10kg
Heater	max temp.	500°C	600°C	350°C
	Power	65W	150W	200W
IRON	Tip SIZE	Φ1.0~4.0mm	Φ10.0mm	50mm x 10mm
	Weight	210g	520g	1,500g
	Hand Switch	nothing		Having
	Cooling	nothing		FAN
Old products(Discontinue)	USM-III / USM-IV	SO-6		USM-28
Applications	Electronic componets PV wire bonding(point) OLED	Electronic device PV wire bonding(line) Al terminal soldering		Target material plyig-up

We supprte the dipping ultrasonic soldering pot, the jet type ultrasonic soldering machine and the auto soldering machines.

Please feel free to get in touch with us.



Soul in Technology

KURODA TECHNO CO.,Ltd.

Ultrasonic Soldering System

SUNBONDER® USM-5

SUNBONDER is an ultrasonic soldering device that produces high quality soldered joints. The soldering iron consists of a high performance sheath heater and transducer, supplying heat and ultrasonic oscillations to the tip. Using CERASOLZER, a solder alloy especially formulated for use with the SUNBONDER, you can easily solder directly to glass, ceramics and other low solderability materials, such as Al, Mo, or stainless steel.

Ultrasonic soldering mechanism

Ordinary soldering join metals by eliminate oxide surface by using flux and disperse mutual metals by accelerate the wetting of a metal and a solder.

SUNBONDER helps this working by ultrasonic energy.

The high performance soldering is implemented by the cavitation effect which break the oxide surface and eliminate the bubbles in solder.

You can easily solder directly to glass, ceramics and other low solderability materials by the application of this law.

Soldering to glass, ceramics and low solderability metals

CERASOLZER is used for soldering to glass, ceramic and low solderability metals. CERASOLZER is a special solder alloy with high oxygen affinity metal.

A strong chemical bond of Zinc and Oxygen is achieved between the substrate and CERASOLZER by applying ultrasonic oscillation with SUNBONDER device to the melting CERASOLZER solder alloy.

This superior bonding technique provides an excellent airtight, weatherproof, humidity resistant seal as well as joints with good electro-conductivity between interconnected layers.

SUNBONDER features

【Special soldering】

Direct soldering to glass, ceramics, low solderability metals without Flux.

【Performance】

Stable ultrasonic frequency and temperature with new feedback system.

【Oscillation】

Adjustable ultrasonic-power output.

【Temperature】

Heater temperature is possible to adjust at intervals of 10°C.

【Display】

Frequency, power, heater temperature and amplitude

Accessories

Foot Switch	1
Soldering iron stand	1
Power source cord	1
Spanner for changing tip	2
Fuse	2

OPTION

Custom tip

External Control (Analog 0-10V)

PC control (LAN)

CE ※No correspond to USM-528



For operating the device, refer to the instruction manuals.
Don't use near water, under conditions of high humidity,
dust and soot filled places,
to avoid electric shock, fire or breakdown.

 Soul in Technology
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